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AN 105:180503 HCA
TI Manufacture of high-**purity** electrolytic **copper**
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PA Sumitomo Metal Mining Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 3 pp.
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AB A high-**purity** **Cu** sulfate bath contg. 90-220 g/L free SO42- is electrolyzed, using an electrolytic **Cu** anode, at a cathode c.d. of .ltoreq.2.5 A/dm2 and .ltoreq.40.degree. to give an electrolytic cathode **Cu** of **purity** .gtoreq.**99**.**999** wt.%. The refined **Cu** has excellent elongation properties and is useful as bonding for semiconductor devices, wires for motors, etc. Thus, a bath contg. **Cu** 42 and SO42- 93 g/L was electrolyzed at 25.degree. and at a cathode c.d. of 1.5 A/dm2, using a Ti cathode and an electrolytic Cu anode (**purity** 99.99 wt.%) which was placed in a Tetron 501 **B** box to deposit high-**purity** **Cu** contg. S <1, **Ag** <1, Fe <0.6, and Si <1 ppm on the cathode.